



SECT. B-B

SECT. A-A

NOTES.

- 適合ハウジング: 501330-**** / 501939-****
APPLICABLE HOUSING: 501330-**** / 501939-****
- メッキ仕様
PLATING
錫メッキ: 1.0μmMIN. リフロー処理(前メッキ)
Sn: 1.0μmMIN. REFLOW TREATMENT (PRE-PLATED)
- 刻印は裏面から実施
PUNCH SIDE: OTHER SIDE
MXJ 金型番号(番号無しの製品もあります.)
Die No. (There is Non-Mark Item)
TREAD MARK

501334-0100	バラ状 LOOSE
501334-0000	連鎖状 CHAIN
MATERIAL NO.	端子形状 FORM

MATERIAL リン青銅 PHOSPHOR BRONZE t=0.12	REVISED EC NO.: J2009-0651 DRW: NAKATA 2008/09/16 CHKD: MATSUMOTO 2008/09/16 APPR: NUKITA 2008/09/16	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
FINISH SEE NOTE		10 UNDER ±0.2	DRAWN BY NYOSHIDA	DATE 2004/07/29	TITLE 1.0 WIRE TO BOARD CONN. CRIMP REC TERMINAL (SN) -LEAD FREE-		
WIRE RANGE AWG #28-32		10 OVER 30 UNDER ±0.25	CHECKED BY MYAGI	DATE 2004/07/29	MOLEX INCORPORATED		
INS. RANGE φ0.4-0.8		30 OVER ±0.3	APPROVED BY MIYAZAWA	DATE 2004/07/29	DOCUMENT NO. SD-501334-001		
		ANGULAR ±3°	MATERIAL NO. SEE TABLE	SIZE A3	SHEET NO. 1 OF 1		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				